Ira A. Fulton Schools of Engineering

SUMMER 2026

Advanced Semiconductor Packaging Program

Arizona State University – Tempe Campus

Program Overview

6-week immersive Research Experience for Undergraduates (REU) focused on advanced semiconductor packaging and heterogeneous integration. Work inside ASU's Nanofab and MacroTechnology Works (MTW) facilities while engaging with industry leaders including Intel and Deca Technologies.

What You Receive

- $4,000 Student Stipend
- On-Campus Housing
- Hands-on cleanroom & packaging lab access
- Industry site visits (including Intel)
- Faculty & graduate student mentorship
- Professional networking opportunities

What You'll Learn

- 2.5D & 3D Integration (EMIB, Foveros, Fan-Out)
- Semiconductor Packaging & Assembly
- Reliability & Failure Analysis
- Yield Optimization & Testing
- Multi-Physics Modeling
- Cleanroom Processing & SMT Assembly

Who Should Apply

Undergraduate students in Electrical Engineering, Computer Engineering, Materials Science, Mechanical Engineering, Physics, or related STEM disciplines. Students from ASU, University of Arizona, NAU, and Maricopa Community Colleges are encouraged to apply.

Program Details

- Duration: June 1st -July 15th
- Location: ASU Tempe Campus
- Cohort Size: 24 Students Selected

Apply Now Advanced Semiconductor Packaging Program

Application Deadline: April 15th

Please Contact: Snow Piel at TUYET-TRANG.LAM@asu.edu if you have any questions